

Silizium-Differential-Fotodiode

Silicon Differential Photodiode

Lead (Pb) Free Product - RoHS Compliant

BPX 48



Wesentliche Merkmale

- Speziell geeignet für Anwendungen im Bereich von 400 nm bis 1100 nm
- Hohe Fotoempfindlichkeit
- DIL-Plastikbauform mit hoher Packungsdichte
- Doppeldiode mit extrem hoher Gleichmäßigkeit

Anwendungen

- Nachlaufsteuerung
- Kantenführungen
- Weg- bzw. Winkelabtastungen
- Industrieelektronik
- „Messen/Steuern/Regeln“

Features

- Especially suitable for applications from 400 nm to 1100 nm
- High photosensitivity
- DIL plastic package with high packing density
- Double diode with extremely high homogeneousness

Application

- Follow-up control
- Edge control
- Path and angle scanning
- Industrial electronics
- For control and drive circuits

Typ Type	Bestellnummer Ordering Code
BPX 48	Q62702P0017S0001

Grenzwerte
Maximum Ratings

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Betriebs- und Lagertemperatur Operating and storage temperature range	$T_{op}; T_{stg}$	- 40 ... + 80	°C
Sperrspannung Reverse voltage	V_R	10	V
Verlustleistung, $T_A = 25\text{ °C}$ Total power dissipation	P_{tot}	50	mW

Kennwerte ($T_A = 25\text{ °C}$) für jede Einzeldiode
Characteristics ($T_A = 25\text{ °C}$) per single diode system

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Fotostrom Photocurrent $V_R = 5\text{ V}$, Normlicht/standard light A, $T = 2856\text{ K}$, $E_V = 1000\text{ lx}$	I_P	24 (≥ 15)	μA
Wellenlänge der max. Fotoempfindlichkeit Wavelength of max. sensitivity	$\lambda_{S\text{ max}}$	900	nm
Spektraler Bereich der Fotoempfindlichkeit $S = 10\%$ von S_{max} Spectral range of sensitivity $S = 10\%$ of S_{max}	λ	400 ... 1150	nm
Bestrahlungsempfindliche Fläche Radiant sensitive area	A	1.54	mm^2
Abmessung der bestrahlungsempfindlichen Fläche Dimensions of radiant sensitive area	$L \times B$ $L \times W$	0.7×2.2	$\text{mm} \times \text{mm}$
Halbwinkel Half angle	φ	± 60	Grad deg.
Dunkelstrom, $V_R = 10\text{ V}$ Dark current	I_R	10 (≤ 100)	nA
Spektrale Fotoempfindlichkeit Spectral sensitivity $\lambda = 850\text{ nm}$	S_λ	0.55	A/W

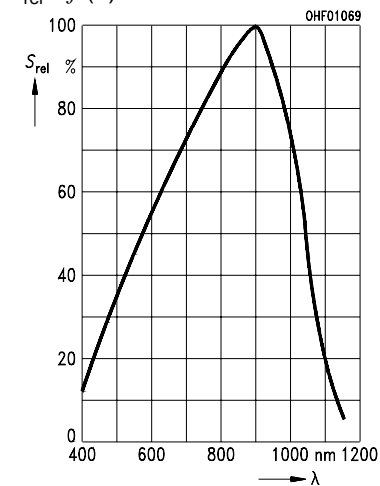
Kennwerte ($T_A = 25\text{ °C}$) für jede Einzeldiode

Characteristics ($T_A = 25\text{ °C}$) per single diode system (cont'd)

Bezeichnung Parameter	Symbol Symbol	Wert Value	Einheit Unit
Max. Abweichung der Fotoempfindlichkeit der Systeme vom Mittelwert Max. deviation of the system spectral sensitivity from the average	ΔS	± 5	%
Quantenausbeute Quantum yield $\lambda = 850\text{ nm}$	η	0.8	<u>Electrons</u> Photon
Leerlaufspannung Open-circuit voltage $E_V = 1000\text{ lx}$, Normlicht/standard light A, $T = 2856\text{ K}$	V_O	330 (≥ 280)	mV
Kurzschlussstrom Short-circuit current $E_V = 1000\text{ lx}$, Normlicht/standard light A, $T = 2856\text{ K}$	I_{SC}	24	μA
Anstiegs- und Abfallzeit des Fotostromes Rise and fall time of the photocurrent $R_L = 1\text{ k}\Omega$; $V_R = 5\text{ V}$; $\lambda = 850\text{ nm}$; $I_p = 20\text{ }\mu\text{A}$	t_r, t_f	500	ns
Durchlassspannung, $I_F = 40\text{ mA}$, $E = 0$ Forward voltage	V_F	1.3	V
Kapazität, $V_R = 0\text{ V}$, $f = 1\text{ MHz}$, $E = 0$ Capacitance	C_0	25	pF
Temperaturkoeffizient von V_O Temperature coefficient of V_O	TC_V	-2.6	mV/K
Temperaturkoeffizient von I_{SC} Temperature coefficient of I_{SC} Normlicht/standard light A	TC_I	0.18	%/K
Rauschäquivalente Strahlungsleistung Noise equivalent power $V_R = 10\text{ V}$, $\lambda = 950\text{ nm}$	NEP	1.0×10^{-13}	$\frac{\text{W}}{\sqrt{\text{Hz}}}$
Nachweisgrenze, $V_R = 10\text{ V}$, $\lambda = 950\text{ nm}$ Detection limit	D^*	1.2×10^{12}	$\frac{\text{cm} \times \sqrt{\text{Hz}}}{\text{W}}$

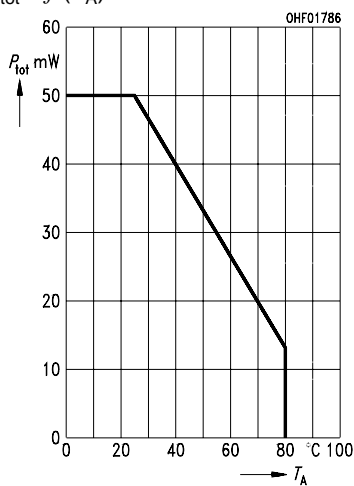
Relative Spectral Sensitivity

$S_{rel} = f(\lambda)$

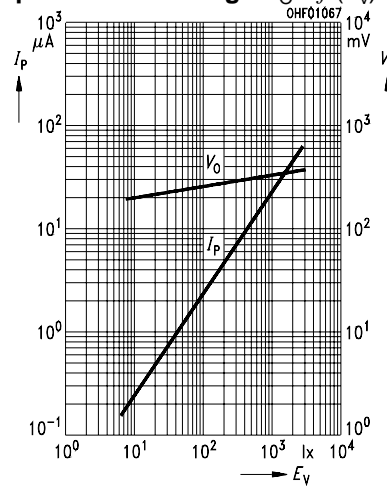


Total Power Dissipation

$P_{tot} = f(T_A)$

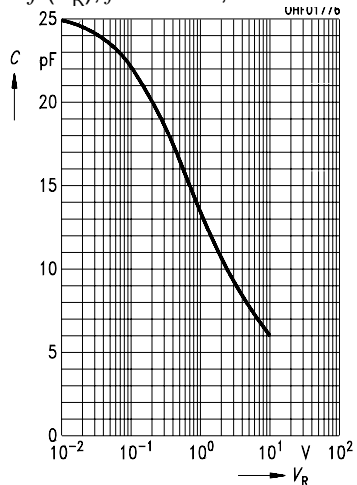


**Photocurrent $I_P = f(E_v)$, $V_R = 5 V$
Open-Circuit Voltage $V_O = f(E_v)$**



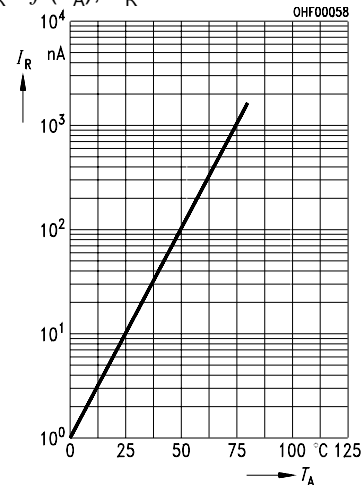
Capacitance

$C = f(V_R), f = 1 MHz, E = 0$



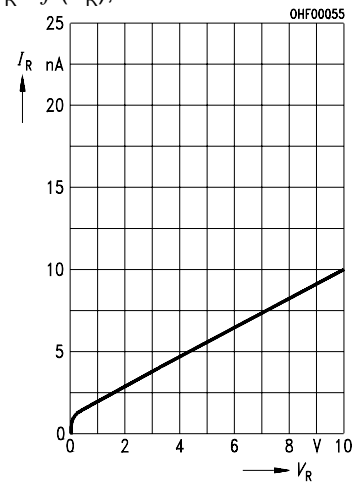
Dark Current

$I_R = f(T_A), V_R = 10 V$



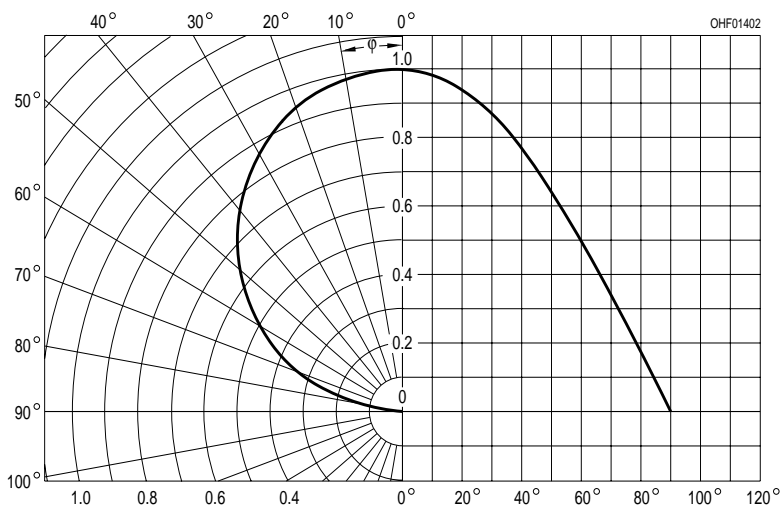
Dark Current

$I_R = f(V_R), E = 0$

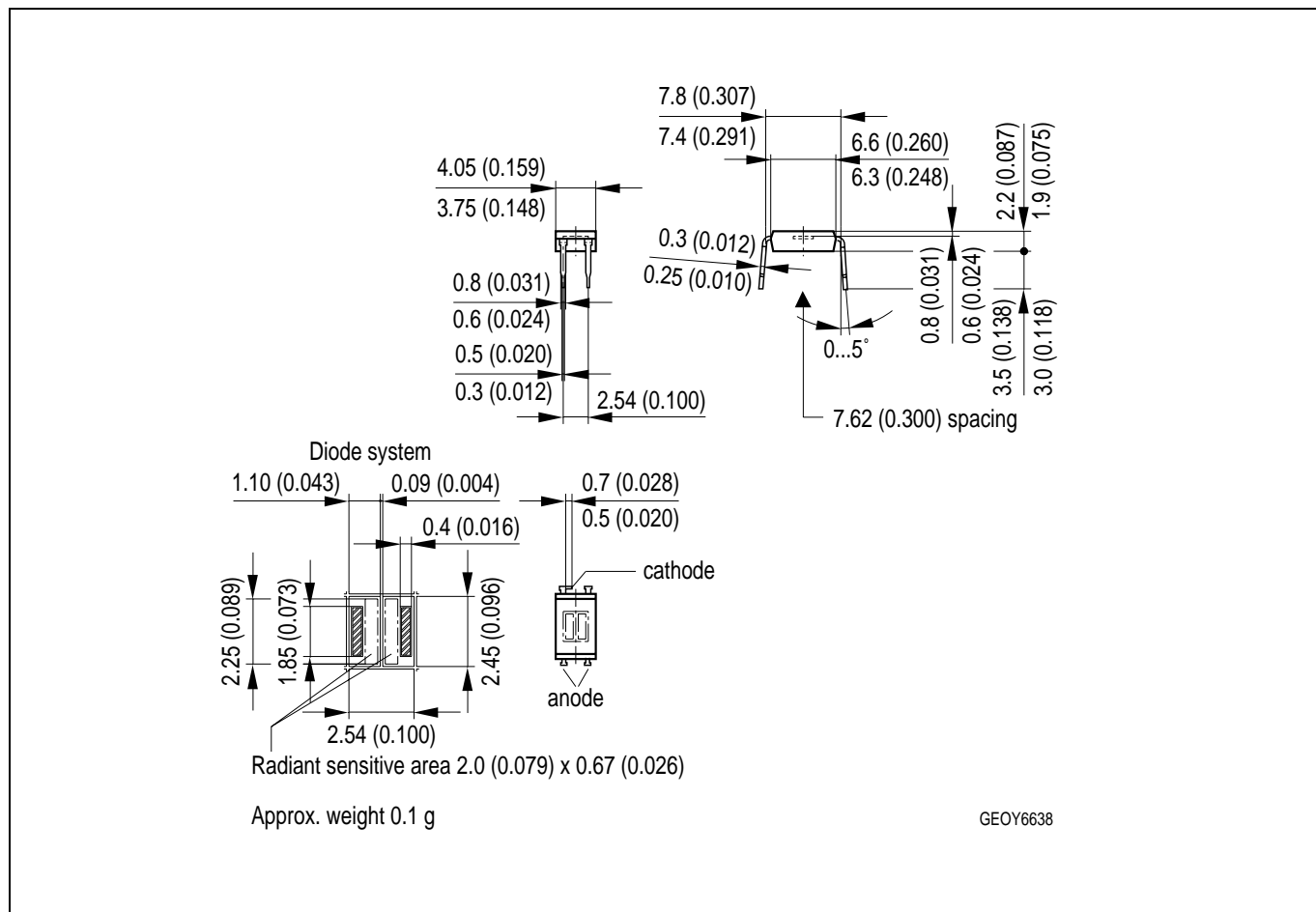


Directional Characteristics

$S_{rel} = f(\varphi)$



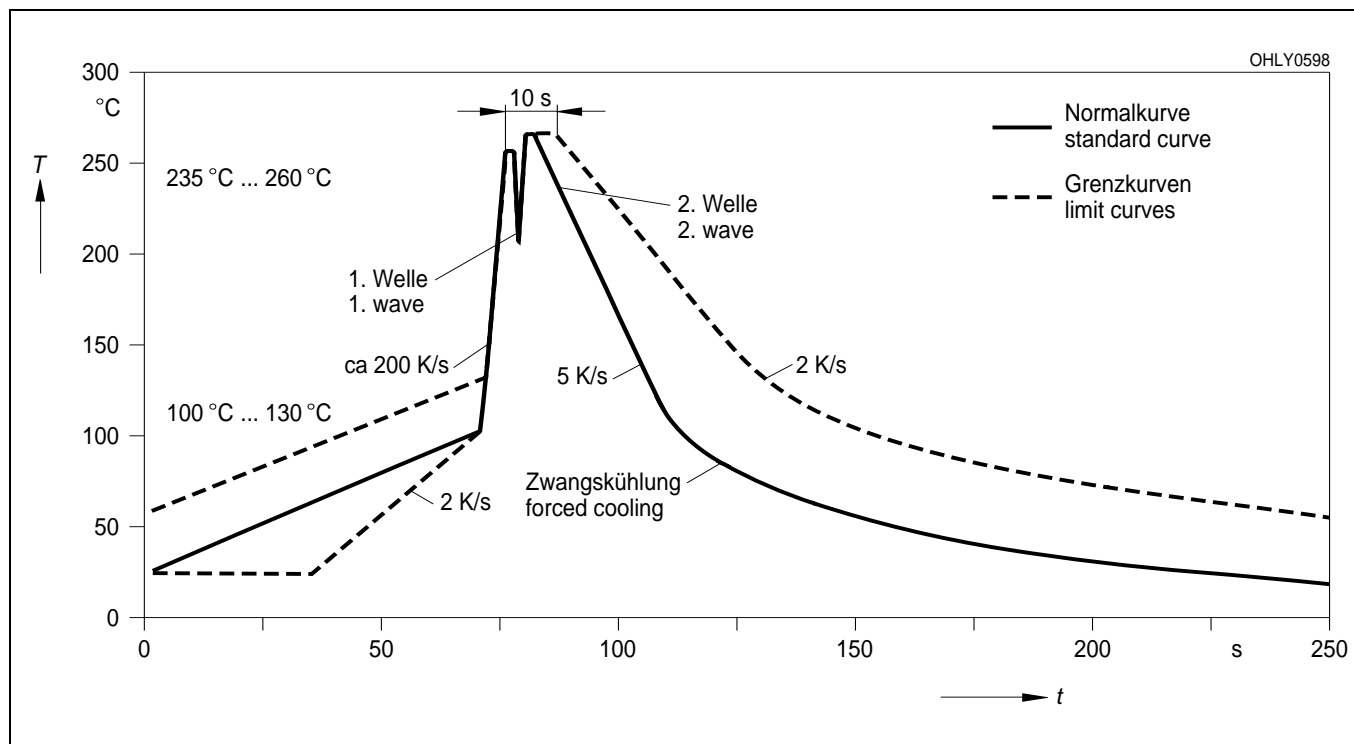
Maßzeichnung
Package Outlines



Maße in mm (inch) / Dimensions in mm (inch).

Lötbedingungen
Soldering Conditions
Wellenlöten (TTW)
TTW Soldering

(nach CECC 00802)
(acc. to CECC 00802)



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EU RoHS and China RoHS compliant product



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